

	Type	L #	Hits	Search Text	DBs	Time Stamp
1	IS&R	L.1	7170	(257/751,752,753,758,762,767,773,774).CCLS.	USPAT	2008/07/07 05:27
2	IS&R	L.2	5213	(257/751,752,753,758,762,767,773,774).CCLS.	US-PGPUB; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	2008/07/07 05:28
3	IS&R	L.3	7646	(438/118,622,627,629,637,643,653,685,687).CCLS.	USPAT	2008/07/07 05:34
4	IS&R	L.4	5028	(438/118,622,627,629,637,643,653,685,687).CCLS.	US-PGPUB; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	2008/07/07 05:34
5	BRS	L.7	788	(substrate) with (recess trench groove) and (barrier diffusion) and (seed) and (metal conductor conductive) with (within)	USPAT	2008/07/07 05:49
6	BRS	L.8	193	7 and (dielectric insulating insulation) with (within) with (recess groove trench)	USPAT	2008/07/07 05:50
7	BRS	L.9	1015	(substrate) with (recess trench groove) and (barrier diffusion) and (seed) and (metal conductor conductive) with (within)	US-PGPUB; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	2008/07/07 05:51
8	BRS	L.10	257	9 and (dielectric insulating insulation) with (within) with (recess groove trench)	US-PGPUB; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	2008/07/07 05:51
9	BRS	L.11	3	((substrate) with (recess trench groove) and (barrier diffusion) and (seed) and (metal conductor conductive) with (within) and (dielectric insulating insulation) with (within) with (recess groove trench)).clm.	USPAT	2008/07/07 05:53